~~Patent~~ Claims:

1. A method for manufacturing an object, the method comprising the steps of:

(a) providing a wafer comprising ~~a multitude of~~ semi-finished objects;

(b) separating said wafer into ~~parts referred to as~~ sub-wafers, at least one of said sub-wafers comprising a plurality of said semi-finished objects;

(c) processing at least a portion of said plurality of semi-finished objects by subjecting said at least one of said sub-wafers to at least one processing step.

~~2. The method according to claim 1, wherein step (c) is carried out while said plurality of said semi-finished objects is comprised in said sub-wafer.~~

~~3. The method according to claim 1 or claim 2~~, wherein said at least one processing step is applied to a separation face of said sub-wafer originating from step (b).

2. The method according to claim 1, wherein said portion comprises at least two of said plurality of semi-finished objects.

3. The method according to claim 1, wherein said portion comprises at least half of said plurality of semi-finished objects.

4. A method for manufacturing an object, the method comprising the steps of:

(a) providing a wafer comprising semi-finished objects;

(b) separating said wafer into sub-wafers, at least one of said sub-wafers comprising a plurality of said semi-finished objects;

(c) processing at least a portion of said plurality of semi-finished objects by subjecting said at least one of said sub-wafers to at least one processing step, wherein said at least one processing step comprises creating a slanted side wall of said sub-wafer slanted with respect to a lateral plane, wherein creating said slanted side wall is accomplished by removing material from said sub-wafer.

5. The method according to claim 4, wherein step (c) is carried out while said plurality of said semi-finished objects is comprised in said sub-wafer.

4~~6~~. The method according to ~~one of~~ claim~~s 1 to 3~~4, wherein in step (c),

— all the semi-finished objects of said portion of said plurality of semi-finished objects are simultaneously processed; or

— the semi-finished objects of said portion of said plurality of semi-finished objects are subsequently processed.

5~~7~~. The method according to ~~one of~~ claim~~s 1 to 4~~, wherein in step (c), each of said semi-finished objects of said at least one sub-wafer is processed by subjecting said at least one sub-wafer to at least one processing step.

6~~8~~. The method according to ~~one of~~ claim~~s 1 to 5~~4, wherein each of at least two of said sub-wafers comprises a respective plurality of said semi-finished objects ~~each~~, ~~in particular~~ wherein the method comprises carrying out for each respective one of said at least two sub-wafers, the step of

(c') processing at least a portion of the respective plurality of semi-finished objects of the respective sub-wafer by subjecting the respective sub-wafer to said at least one processing step.

~~7~~9. The method according to ~~one of~~ claim~~s 1 to 6~~4, wherein in said at least one sub-wafer, said plurality of said semi-finished objects forms a repetitive one-dimensional arrangement of said semi-finished objects.

~~8~~10. The method according to ~~one of~~ claim~~s 1 to 7~~4, wherein in said at least one sub-wafer, said plurality of said semi-finished objects is arranged along one or two straight lines~~, in particular along one straight line~~.

~~9~~11. The method according to ~~one of~~ claim~~s 1 to 8~~4, wherein said at least one processing step comprises at least one of the group consisting of

- a replication step~~, in particular an embossing step~~;
- a mechanical processing step;
- a polishing step;
- a grinding step;
- a cutting step;~~, in particular a cutting step producing at least one cut face having a surface normal inclined with respect to the vertical; //(the term "vertical" referring to the shape of the wafer)~~
- a chemical processing step;
- a lithographic step;
- a coating step; and

— an etching step.

~~10~~12. The method according to ~~one of claims 1 to 9, wherein said at least one processing step comprises creating a slanted side wall of said sub-wafer slanted with respect to the lateral plane, in particular wherein said creating said slanted side wall is accomplished by removing material from said sub-wafer.~~

~~11. The method according to one of~~ claims ~~1 to 10~~4, wherein said object is at least one of the group consisting of:

— an optical element;

— an optical device;

— ~~a substrate, in particular~~ a substrate comprising at least one slanted face ~~and/or a substrate for an optical assembly or for an optical sub-assembly~~;

— ~~an optical sub-assembly, in particular~~ an optical sub-assembly comprising a substrate on which a light emitter is mounted, ~~more particularly~~ wherein said substrate on which a light emitter is mounted has at least one slanted face and/or wherein said light emitter is an edge-emitting light emitter and/or a laser;

— an opto-electronic module;

— an optical system;

— a light-guiding device~~, in particular a light guide element~~;

— a micro-mechanical element;

— a micro-electro-mechanical element;

— a micro-electro-mechanical system.

~~12~~13. The method according to ~~one of~~ claim~~s 1 to 11~~4, wherein said wafer is at least partially~~, in particular prevailingly,~~ made of a transparent ~~material, in particular of a transparent~~ polymer or of a glass.

~~13~~14. The method according to ~~one of~~ claim~~s 1 to 12~~4, comprising carrying out, after carrying out step (c), the step of

(d) separating said at least one sub-wafer into a plurality of parts, ~~in particular,~~ wherein each part comprises one of said processed semi-finished objects~~, more particularly wherein one of said parts is said object~~.

~~14~~15. The method according to ~~one of~~ claim~~s 1 to 13~~4, comprising carrying out, before carrying out step (b), the step of

(e) manufacturing said wafer.

~~15. The method according to one of claims 1 to 14, wherein said portion comprises at least two of said plurality of semi-finished objects.~~

~~16. The method according to one of claims 1 to 15, wherein said portion comprises at least half of said plurality of semi-finished objects.~~

~~17. A semi-finished product comprising a side wall running along a straight line and a plurality of semi-finished objects, at least a portion of said plurality of semi-finished objects being arranged along a line parallel to said side wall.~~

~~18. The semi-finished product according to claim 17, which is of bar- or plate- or rod-shape.~~

~~19. The semi-finished product according to claim 17 or claim 18, wherein each of said semi-finished objects of said portion of said plurality of semi-finished objects comprises a face formed by said side wall, in particular wherein each of said semi-finished objects of said plurality of semi-finished objects comprises a face formed by said side wall.~~

~~20. The semi-finished product according to one of claims 17 to 19, wherein all of said plurality of semi-finished objects are arranged along one or two lines parallel to said side wall, in particular along one such line.~~

~~21. The semi-finished product according to one of claims 17 to 20, wherein said side wall is slanted.~~

~~22. The semi-finished product according to one of claims 17 to 21, wherein said side wall is provided with at least one of the group consisting of~~

- ~~a coating;~~
- ~~a replicated structure, in particular a structure obtained using embossing;~~
- ~~an optical structure, in particular wherein said optical structure comprises curved faces and/or comprises refractive and/or diffractive elements;~~
- ~~a passive optical component directly or indirectly attached to said side wall;~~

~~— an active optical component directly or indirectly attached to said side wall.~~

~~23. A method for manufacturing a device, said device comprising at least one object, the method comprising manufacturing said at least one object according to a method as claimed in one of claims 1 to 16.~~

~~24. The method according to claim 23, comprising the step of attaching said at least one object to at least one other constituent of said device, in particular mounting said at least one object at or inside a housing of said device.~~

~~25. The method according to claim 23 or claim 24, wherein said device is at least one of the group consisting of~~

~~— an electronic device, in particular hand-held electronic device;~~

~~— an electro-optic device;~~

~~— a hand-held device, in particular a hand-held optics device;~~

~~— a communication device, in particular a mobile communication device;~~

~~— a smart phone;~~

~~— a digital music player;~~

~~— a photographic device, in particular a photo camera and/or a video camera.~~